

## PCN#20200904000.1 Qualification of HFTF as an additional assembly site for select Devices Change Notification / Sample Request

Date:September 09, 2020To:FLEXTRONICS PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

#### 20200904000.1 Attachment: 1

#### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

#### DEVICE

SN74LVC1G125DBVR SN74LVC2G125DCUR SN74LVC1G0125DBVR SN74LVC1G07DCKR SN74LVC1G07DCKR SN74LVC1G04DCKR SN74LVC1G07DCKR SN74LVC1G07DCKR SN74LVC1G04DCKR SN74LVC2G125DCUR SN74LVC2G125DCUR

#### **CUSTOMER PART NUMBER**

CIE-N0037839 CIE-N0110205 CIS-15-10442-01 CIS-15-6939-02 CISU-15-10312-01 CISU-15-3254-02 CISU-15-6939-02 CISU-15-7140-02 NORN0110205 ODM-IBM-77P9401

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b> 20200904000.1			PCN			Date:	Sept 09, 2020	
Title: Qualification of HFTF as an additional assembly site for select Devices								
Customer Contact: PCN Manager		<u>Manager</u>	Dept: Quality Services					
Proposed 1 <sup>st</sup> Ship Date: Dec		Dec 09, 2	Dec 09, 2020 Esti		Estim	nated Sample Availability:		Date provided at sample request
Change Type:								
Assembly Site			Design			Wafer Bump Site		
Assembly Process			Data Sheet			Wafer Bump Material		
Assembly Materials			Part number change			Wafer Bump Process		
Mechanical Specification			Test Site			Wafer Fab Site		
Packing/Shipping/Labeling			Test Process			Wafer Fab Materials		
Wafer Fab Process								
PCN Details								

#### **Description of Change:**

Texas Instruments Incorporated is announcing the qualification of HFTF as an alternate Assembly site for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:

#### **Material Differences:**

	ASEWH	HIT	HNA	HFTF
Mount Compound	1120999A2	RZ241C	400180	SID# A-18
Mold Compound	4020039A1	RM500F	450179	SID#R-31
Lead Finish	NiPdAu	Matte Sn	NiPdAu	Matte Sn
Wire type	Au	Au	Au	Cu

Upon expiry of this PCN TI will combine lead free solutions in a single <u>standard part number</u>, for the devices in group 2. For example; <u>SN74LVC1G04DCKR</u> – can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. **SN74LVC1G04DCKRG4**."

Example:

 Customer order for 7500 units of *SN74LVC1G04DCKR* with 2500 units SPQ (Standard Pack Quantity per Reel).

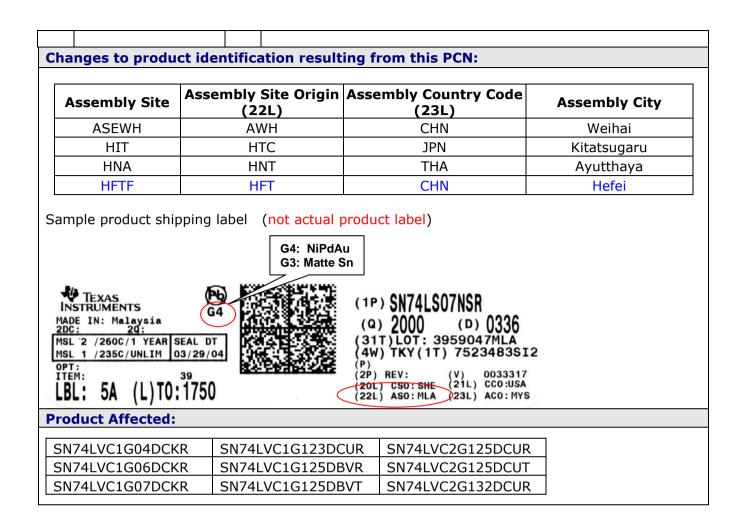
- TI can satisfy the above order in one of the following ways.
  - I. 3 Reels of NiPdAu finish.
  - II. 3 Reels of Matte Sn finish
  - III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.
  - IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish.

### **Reason for Change:**

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative): None

Anticipated impact on Material Declaration				
	No Impact to the Material Declaration		Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/guality/docs/materialcontentsearch.tsp	



# **Qualification Report**

Approve Date 30-Oct-2019

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration Qual Device: <u>LSF0102DCUR</u>		Qual Device: <u>SN74LVC1G123DCUR</u>	
PC	PreCon Level 1	Level 1-260C	3/231/0	3/231/0	
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0	
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0	
HTOL	Life Test, 125C	1000 Hours	3/231/0	3/231/0	
LI	Lead Fatigue	Leads	3/66/0	-	
LI	Lead Pull	Leads	3/18/0	-	
MISC	Salt Atmosphere	24 Hours	3/66/0	-	
SD	Surface Mount Solderability	PB	3/66/0	-	
SD	Surface Mount Solderability	PB-Free	3/66/0	-	
DS	Die Shear		3/30/0	3/30/0	
PKG	Lead Finish Adhesion	Leads	3/45/0	-	
WBP	Bond Pull	Wires	3/228/0	3/228/0	

Туре	Test Name / Condition	Test Name / Condition Duration		Qual Device: <u>SN74LVC1G123DCUR</u>	
WBS	Bond Shear	Wires	3/228/0	3/228/0	
FLAM	Flammability (IEC 695-2-2)		3/15/0	-	
FLAM	Flammability (UL 94V-0)		3/15/0	-	
FLAM	Flammability (UL-1694)		3/15/0	-	

- QBS: Qual By Similarity

- Qual Device SN74LVC1G123DCUR is qualified at LEVEL1-260CG

- Qual Device LSF0102DCUR is qualified at LEVEL1-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

## **Qualification Report**

Approve Date 09-Jun-2017

#### **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duratio n	Qual Device: SN74AHC1G14DBV R	Qual Device: SN74CBTLV1G125DBV R	Qual Device: SN74LVC1G17DBV R	Qual Device: TL431AIDBV R	Qual Device: TLVH431AIDBV R
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
AC	Autoclave 121C	144 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
FLA M	Flammability (IEC 695-2-2)		3/15/0	-	-	-	-
FLA M	Flammability (UL 94V-0)		3/15/0	-	-	-	-
FLA M	Flammability (UL-1694)		3/15/0	-	-	-	-
HAS T	Biased HAST, 130C/85%R H	96 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
HAS T	Biased HAST, 130C/85%R H	192 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
HTO L	Life Test, 150C	300 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
HTSL	High Temp. Storage Bake, 170C	400 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0

HTSL	High Temp. Storage Bake, 170C	600 Hours	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
LI	Lead Fatigue	Leads	3/66/0	-	-	2/44/0	1/22/0
LFA	Lead Finish Adhesion	Leads	3/45/0	-	-	2/30/0	1/15/0
LI	Lead Pull to Destruction	Leads	3/66/0	-	-	2/44/0	1/22/0
PD	Physical Dimensions		3/15/0	-	-	2/10/0	1/5/0
SD	Solderability	Pb	3/66/0	-	-	2/44/0	1/22/0
SD	Solderability	Pb Free	3/66/0	-	-	2/44/0	1/22/0
тс	Temperature Cycle, - 65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
тс	Temperature Cycle, - 65/150C	750 Cycles	3/231/0	3/231/0	3/231/0	2/154/0	1/77/0
DSS	Die Shear	Die	3/30/0	3/30/0	3/30/0	2/20/0	1/10/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	2/152/0	1/76/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	2/152/0	1/76/0
MSL	Moisture Sensitivity Level	1-260C	3/36/0	-	-	2/24/0	1/12/0
SA	Salt Atmosphere	24 Hours	3/66/0	-	-	-	-
XR	X-Ray	(top side only)	3/15/0	3/15/0	3/15/0	2/10/0	1/5/0
_	- OBS: Qual By Similarity						

- QBS: Qual By Similarity

- Qual Device SN74AHC1G14DBVR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

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